

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20040109046"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:25
S2	4813	347/20,50,54,68-72.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:25
S3	31343	(fpc (flexible adj printed adj circuit) wir\$3) with (protrusion protrud\$3 (draw adj out) (jut adj out))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:27
S4	63	(fpc (flexible adj printed adj circuit) wir\$3) with (protrusion protrud\$3 (draw adj out) (jut adj out)) same ((electric\$4 with connect) with (power supply))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28
S5	0	S2 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28
S6	158	(fpc (flexible adj printed adj circuit) wir\$3) same (protrusion protrud\$3 (draw adj out) (jut adj out)) same ((electric\$4 with connect) with (power supply))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28
S7	336	(fpc (flexible adj printed adj circuit) wir\$3) same (protrusion protrud\$3 (draw adj out) (jut adj out)) same ((electric\$4 with connect) same (power supply))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:40
S8	0	S2 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28

S9	0	S2 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28
S10	60992	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:29
S11	1	S7 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:29
S12	53	S2 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:29
S13	6	("4940413" "5227812" "5796416" "6186613" "6188414" "6325488").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/06 13:00
S14	2	jp-2000108344-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:30
S15	2	jp-2000094673-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:28
S16	82937	(ink liquid fluid) same (drip\$3 leak\$3) with (adhesive glu\$3 seal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:36
S17	187	S2 and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:38

S18	936	(ink liquid fluid) same (drip\$3 leak\$3) with (adhesive glu\$3 seal\$3) with (electrode (electric\$2 adj connection)))".	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:33
S19	936	(ink liquid fluid) same (drip\$3 leak\$3) with (adhesive glu\$3 seal\$3) with (electrode (electric\$2 adj connection))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:42
S20	4	S2 and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:33
S21	96	S2 and S16 and piezoelectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:36
S22	2024	(ink liquid fluid) same (drip\$3 leak\$3) same (adhesive glu\$3 seal\$3) with (electrode (electric\$2 adj connection)) same electr\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:45
S23	13	S2 and S22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:42
S24	2024	(ink liquid fluid) same (drip\$3 leak\$3) same (adhesive glu\$3 seal\$3) with (electrode (electric\$2 adj connection)) with electr\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:45
S25	4941	(ink liquid fluid) same (drip\$3 leak\$3) same (adhesive glu\$3 seal\$3) with electr\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:45

S26	15	S2 and S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:45
S27	0	("6802596").URPN.	USPAT	OR	ON	2005/04/06 13:55
S28	4810	347/20,50,54,68-72.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:40
S29	2997244	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:41
S30	162278	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable) with (seal\$3 glue bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:42
S31	286	S28 and S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:41
S32	79	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable) with (seal\$3 glue bond\$3) with (print\$2head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:45
S33	87	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable flexible) with (seal\$3 glue bond\$3) with (print\$3head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:46
S34	87	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable flexible) with (seal\$3 glue bond\$3 relief) with (print\$3head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:47

S35	88	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable flexible) with (seal\$3 glue bond\$3 stress strain) with (print\$3head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:05
S36	6734	(protrusion protrud\$3 through) with (seal\$3 glu\$3 bond\$3) with (electrical same (wire fpc circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:07
S37	4810	347/20,50,54,68-72.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:11
S38	6734	(protrusion protrud\$3 through) with (seal\$3 glu\$3 bond\$3) with (electrical same (wire fpc circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:11
S39	20	S37 and S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:18
S40	263	(electric\$2 near5 connection) with (internal external) with piezoelectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:25
S41	24	S37 and S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:20
S42	6	("5311219" "5755019" "5761783" "5971522" "6073321" "6106106").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/07 09:22
S43	113	(electric\$2 near5 connection) same (internal external) with piezoelectric same (adhesive seal\$3 bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:26